



DEFENSE LOGISTICS AGENCY
WEAPONS SUPPORT
P.O. BOX 3990
COLUMBUS, OHIO 43218-3990

February 4, 2026

Mr. Steven White
Director of Quality
Micross Components Orlando (MCO)
1810 S. Orange Blossom Trail
Apopka, FL 32703

Dear Mr. White:

Re: Q and V Level Assembly and Test Certification; MIL-PRF-38535; FSC 5962; VQC-26-040129; Control Number 094628

Micross Components Orlando (MCO) has demonstrated to the DLA Weapons Support Columbus that it complies with MIL-PRF-38535, the performance specification used by the Department of War for monolithic integrated circuits.

Micross Components Orlando (MCO) is granted Q and V Level Assembly and Test Certification for the process flows and materials used to assemble and test QML products for the quality assurance levels listed in the enclosure. This assembly and test certification listing includes subcontractors approved by MCO and as documented in their Quality Management Plan.

Testing must be performed using the facilities and methods listed in the Laboratory Suitability letter DLA Weapons Support Columbus VQC-26-040130, or at facilities approved by MCO's Technical Review Board (TRB) using its MIL-PRF-38535 Quality Management Program Plan.

This certification is subject to the conditions in DoD 4120.24-M, Defense Standardization Program and SD-6.

All the facilities mentioned on in the enclosure are subject to an audit by the DLA Weapons Support Columbus Qualifying Activity at any time.

MCO shall notify the DLA Weapons Support Columbus Qualifying Activity immediately after learning of a potential issuance of a GIDEP alert, problem advisory or major quality/reliability problem on their assembly and test processes. Failure to provide prior notification may be grounds for removal of their MIL-PRF-38535, Q and V Assembly and Test certification.

In addition, it is requested that the following activities be reported promptly to DLA Weapons Support Columbus:

- Changes to certified facilities, process flows, or approved testing subcontractors.
- Problem evaluation and a corrective action when:
 - A Technology Conformance Inspection (TCI) failure has been validated
 - The reliability of shipped parts is questionable.
- Test optimization, including:
 - Implementation - paragraph J.3.12, Appendix J, MIL-PRF-38535
 - Changing, suspending or canceling a prior test optimization
- Additions or deletions of parts in the QML-38535
- Change of company QML contact or other key QML personnel
- Changes in test methods and conditions

This Assembly and Test certification is valid until terminated by written notice from the DLA Weapons Support Columbus Qualifying Activity. If warranted, it may be withdrawn by this center at any time.

If you have any questions please contact Mr. Paul Granchi, at (614) 693-7616.

Sincerely,

MICHAEL S. ADAMS
Chief
Custom Devices Branch

ENCLOSURE

Enclosure to VQC-26-040129

Package Assembly Capabilities:

<u>OPERATION</u>	<u>FACILITY</u>	<u>LOCATION</u>	<u>CAPABILITY</u>
Assembly	Micross Components Orlando (MCO)	1810 S. Orange Blossom Trail Apopka, FL 32703	
Die Attach Material	Micross Components Orlando (MCO)	1810 S. Orange Blossom Trail Apopka, FL 32703	Eutectic 80/20 AuSn, JM7000, 98/2 AuSi
Wire Type and Wire Size	Micross Components Orlando (MCO)	1810 S. Orange Blossom Trail Apopka, FL 32703	Al - 0.8, 1.0, 1.25, 4.0, 5.0
Lead Finish	Micross Components Orlando (MCO)	1810 S. Orange Blossom Trail Apopka, FL 32703	Gold Tin Lead
Sealing	Micross Components Orlando (MCO)	1810 S. Orange Blossom Trail Apopka, FL 32703	Solder seal, Parallel Seam seal, Projection Welding
Screening / Environmental Testing	Micross Components Orlando (MCO)	1810 S. Orange Blossom Trail Apopka, FL 32703	Screening as baselined by lab suitability information letter VQC-22-037042
Subcontractors	Microchip Technology Thailand - MMT	17/2 Moo 18, Suwinthawong Road Tambol Saladang Amphur Bangnumpriew Chachoengsao	MIL-PRF-38535 Q and V assembly and screens in accordance with Micross device specification flow MCO-Q-102.